IRF520 IRF521 IRF522 IRF523 R520 R521

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N-Channel Enhancement-Mode Vertical DMOS Power FETs

Ordering Information

BV _{DSS} / BV _{DGS}	R _{DS(ON)} (max)	l _{D(ON)} (min)	Order Number / Package		
			TO-220	TO-92	
100V		8.0A	IRF520	R520	
60V	0.3Ω	8.0A	IRF521	R521	
100V	0.4Ω	7.0A	IRF522		
60V	0.4Ω	7.0A	IRF523	_	

Features

- ☐ Freedom from secondary breakdown
- □ Low power drive requirement
- □ Ease of paralleling
- $\hfill \square$ Low $\mathbf{C}_{\mathrm{ISS}}$ and fast switching speeds
- □ Excellent thermal stability
- ☐ Integral Source-Drain diode
- ☐ High input impedance and high gain
- ☐ Complementary N- and P-Channel devices

Applications

- ☐ Motor control
- □ Converters
- □ Amplifiers
- □ Switches
- □ Power supply circuits
- Drivers (Relays, Hammers, Solenoids, Lamps, Memories, Displays, Bipolar Transistors, etc.)

Absolute Maximum Ratings

Drain-to-Source Voltage	BV _{oss}		
Drain-to-Gate Voltage	BV _{DGS}		
Gate-to-Source Voltage	± 20V		
Operating and Storage Temperature	-55°C to +150°C		
Soldering Temperature*	300°C		

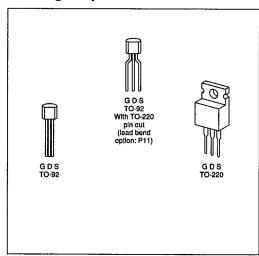
^{*}Distance of 1.6 mm from case for 10 seconds.

Advanced DMOS Technology

These enhancement-mode (normally-off) power transistors utilize a vertical DMOS structure and Supertex's well-proven silicongate manufacturing process. This combination produces devices with the power handling capabilities of bipolar transistors and with the high input impedance and negative temperature coefficient inherent in MOS devices. Characteristic of all MOS structures, these devices are free from thermal runaway and thermally-induced secondary breakdown.

Supertex Vertical DMOS Power FETs are ideally suited to a wide range of switching and amplifying applications where high breakdown voltage, high input impedance, low input capacitance, and fast switching speeds are desired.

Package Options



Thermal Characteristics

IRF520/IRF521/IRF522/IRF523/R520/R521

Package	I _D (continuous)*	I _D (pulsed)*	Power Dissipation @ T _c = 25°C	°C/W	^θ i₃ °C/W	I _{DR}	I _{DRM} *	
IRF520, IRF521	8.0A	32.0A	40W	80	3.12	8.0A	32.0A	
IRF522, IRF523	7.0A	32.0A	40W	80	3.12	8.0A	32.0A	
R520, R521	1.0A	9.0A	1W	170	125	1.0A	9.0A	

^{*}ID (continuous) is limited by max rated Ti.

Electrical Characteristics (@ 25°C unless otherwise specified)

Symbol	Parameter		rameter Min Typ	Max	Unit	Conditions		
BV _{DSS}	Drain-to-Source Breakdown Voltage	IRF520, IRF522, R520 IRF521, IRF523,	100 60			٧	V _{GS} = 0, I _D = 250μA	
V _{GS(th)}	R521 Gate Threshold Voltage		2.0		4.0	V	$V_{GS} = V_{DS}, I_D = 250 \mu A$	
I _{GSS}	Gate Body Leakage				500	nA	$V_{GS} = \pm 20V, V_{DS} = 0$	
I _{oss}	Zero Gate Voltage Drain Current				250		V _{GS} = 0, V _{DS} = Max Rating	
555					1000	μА	$V_{GS} = 0$, $V_{DS} = 0.8$ Max Rating $T_{C} = 125^{\circ}$ C	
I _{D(ON)}	ON-State Drain Current	IRF520, IRF521, R520, R521	8.0			Α	$V_{GS} = 10V$ $V_{DS} > I_{D(ON)} \times R_{DS(ON)}$ Max Rating	
R _{DS(ON)}	Static Drain-to-Source ON-State Resistance	IRF522, IRF523 IRF520, IRF521 R520, R521 IRF522, IRF523	7.0		0.3	Ω	V _{GS} = 10V, I _D = 4.0A	
G _{FS}	Forward Transconductance		1.5	2.9		ប	$V_{DS} > I_{D(ON)} \times R_{DS(ON)}$ Max Rating $I_D = 4.0A$	
C _{ISS}	Input Capacitance				600		V 0 V 05V	
C _{oss}	Common Source Output Capacitance				400	pF	V _{GS} = 0, V _{DS} = 25V f = 1 MHz	
C _{RSS}	Reverse Transfer Capacitance				100			
t _{d(ON)}	Turn-ON Delay Time				40		V O EDV	
t,	Rise Time				70	ns	$V_{DD} = 0.5BV_{DSS}$ $I_{D} = 4.0A$	
t _{d(OFF)}	Turn-OFF Delay Time				100		$V_{\text{ns}} = 0.8 \text{ Max Rating}$	
t,	Fall Time				70		T _{DS} = 0.0 Max rading	
V _{SD}	Diode Forward	IRF520, IRF521 R520, R521			2.5	٧	V _{GS} = 0V, I _{SD} = 1A	
	Voltage Drop	IRF522, IRF523			2.3		$V_{GS} = 0V$, $I_{SD} = 8A$	
t _{rr}	Reverse Recovery Time			280		ns	T _i = 150°C, I _F = 8.0A, dI _{F/dt} = 100A/μS	

Note 1: All D.C. parameters 100% tested at 25°C unless otherwise stated. (Pulse test: 300µs pulse, 2% duty cycle.)
Note 2: All A.C. parameters sample tested.

Switching Waveforms and Test Circuit

